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EUROPEAN PATENT OFFICE

Patent Abstracts of Japan

PUBLICATION NUMBER : 07263733
PUBLICATION DATE : 13-10-95

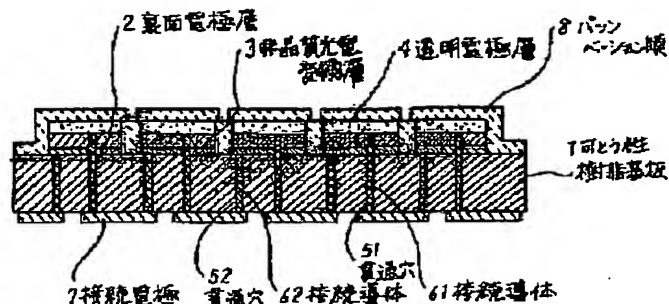
APPLICATION DATE : 23-03-94
APPLICATION NUMBER : 06051477

APPLICANT : FUJI ELECTRIC CO LTD;

INVENTOR : SATO KOKI;

INT.CL. : H01L 31/04 H01L 31/042

TITLE : THIN FILM PHOTOELECTRIC
CONVERSION DEVICE AND
MANUFACTURE THEREOF



ABSTRACT : PURPOSE: To lessen defectives caused by a change of quality in the surfaces of devices in number in a manufacturing process by a method wherein the connection of elements is made on the rear side of a substrate.

CONSTITUTION: Back electrode layers 2, photoelectric conversion amorphous thin film layers 3 which contain at least a P-I-N junction each, and transparent electrode layers 4, are formed on a flexible resin substrate 1, the transparent electrode layer 4 and the back electrode layers 2 are connected together with connecting electrodes 7 formed on the other side of the substrate 1 and conductors 61 and 62 buried in through-holes 51 and 52, and the photoelectric conversion surfaces are covered with passivation films 8. By this constitution, the connecting electrodes 7 formed on the rear side of the substrate can be connected to make them a module after the passivation films 8 are formed, so that a thin film photoelectric conversion device of this constitution is hardly changed in characteristics before a modularizing operation is carried out, since the front side of the device is protected by a passivation film. Therefore, as the light receiving surface of this device is protected, defective devices which occur in transfer before a bonding step, in incorporation into a module, and in bonding can be sharply lessened in number.

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